



CERTIFICATE FOR
Highly Cited Research

in Microelectronics Reliability

Awarded **December, 2016** to

R. Huang

in recognition of the contribution to the quality of the journal made by:

Measurement and analysis of thermal stresses in 3D integrated structures containing through-silicon-vias*

**paper published in 2013 and cited in 2014/2015 up until June 2016 according to data from Scopus*

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